

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
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EPAS ID: PAT7087914

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HANGZHOU CHUANGQIN SENSOR TECHNOLOGY CO., LTD.	12/01/2021

RECEIVING PARTY DATA

Name:	HANGZHOU SILICON-MAGIC SEMICONDUCTOR TECHNOLOGY CO., LTD.
Street Address:	ROOM 1201, NO. 6, LIANG HUI STREET
Internal Address:	XIXING RD, BIN JIANG DISTRICT
City:	HANGZHOU, ZHE JIANG PROVINCE (ZJ)
State/Country:	CHINA

PROPERTY NUMBERS Total: 13

Property Type	Number
Patent Number:	9018062
Patent Number:	9245977
Patent Number:	9171921
Patent Number:	9905636
Patent Number:	10290715
Application Number:	16247007
Application Number:	16853920
Application Number:	17091225
Application Number:	17113305
Application Number:	17235103
Application Number:	17394879
Application Number:	17479314
Application Number:	17508251

CORRESPONDENCE DATA

Fax Number: (704)444-1111

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 7044441000

Email: patent-mail@alston.com

Correspondent Name: ALSTON & BIRD LLP/EMILY SHU

PATENT

Address Line 1: BANK OF AMERICA PLAZA, 101 S. TRYON ST.
Address Line 2: SUITE 4000
Address Line 4: CHARLOTTE, NORTH CAROLINA 28280-4000

ATTORNEY DOCKET NUMBER: 073364/572007

NAME OF SUBMITTER: EMILY SHU

SIGNATURE: /Emily Shu/

DATE SIGNED: 12/22/2021

Total Attachments: 4

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ASSIGNMENT - WORLDWIDE

THIS ASSIGNMENT, made by, **HANGZHOU CHUANGQIN SENSOR TECHNOLOGY CO., LTD.**, having its principal place of business at ROOM 301, NO. 3766 SOUTH CIRCULAR ROAD, HANGZHOU, ZHEJIANG PROVINCE, CHINA 310057, hereinafter referred to as Assignor;

WITNESSETH: That,

WHEREAS, Assignor has previously acquired all right, title, and interest in and to the intellectual property identified on the attached Schedule A, in and to all corresponding patents, patent applications, utility models, design registrations, other rights of exclusion, and/or inventors' certificates in every country or region worldwide, and in and to all inventions represented thereby (all hereinafter referred to collectively as the "Assigned Intellectual Property" on the attached Schedule A); and,

WHEREAS, **HANGZHOU SILICON-MAGIC SEMICONDUCTOR TECHNOLOGY CO., LTD.**, having its principal place of business at ROOM 1201, NO. 06, LIANG HUI STREET, XIXING RD, BIN JIANG DISTRICT, HANGZHOU, ZHE JIANG PROVINCE (ZJ), CHINA, hereinafter referred to as Assignee, is desirous of acquiring the entire right, title, and interest in and to the Assigned Intellectual Property; and

WHEREAS, the parties have agreed to the Assignment hereinafter set forth;

NOW, THEREFORE, To All Whom It May Concern, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, the above Assignor has sold and by these presents does hereby sell, assign, transfer, and convey unto the said Assignee, its successors and assigns, its entire right, title, and interest in and to the Assigned Intellectual Property, together with every priority right that is or may be predicated upon or arise from any of the Intellectual Property; and the right to pursue, collect, and retain in Assignee's name or otherwise, damages and any other remedies arising from any past, present, or future infringement of the Assigned Intellectual Property assigned by this Assignment; all to be held and enjoyed by said Assignee, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by Assignor if this assignment and sale had not been made.

From time to time after the date hereof, at the request of either party hereto, and at the expense of the party so requesting, each of the parties hereto shall execute and deliver to such requesting party such documents and take such other action as such requesting party may reasonably request in order to consummate more effectively the transactions contemplated hereby.

The Assignor further covenants and agrees that, at the time of the execution and delivery of these presents, it possesses full title to the Assigned Intellectual Property, and that it has the unencumbered right and authority to make this Assignment.

IN WITNESS WHEREOF, the Assignor has caused this assignment to be executed this _____ 1st _____ day of _____ December _____, 2021.

ASSIGNOR:

HANGZHOU CHUANGQIN SENSOR TECHNOLOGY CO., LTD

By: Zhuying Ji

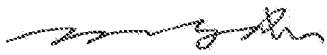
Print Name: Zhuying Ji

Title: Chairman

IN WITNESS WHEREOF, the Assignee has caused this assignment to be executed this
__1st__ day of __December__ , 2021__.

ASSIGNEE:

HANGZHOU SILICON-MAGIC SEMICONDUCTOR
TECHNOLOGY CO., LTD

By:  _____

Print Name: _____ Yuancheng Ren _____

Title: _____ Chairman _____

Assignment Between
**HANGZHOU CHUANGQIN SENSOR TECHNOLOGY CO., LTD and HANGZHOU
SILICON-MAGIC SEMICONDUCTOR TECHNOLOGY CO., LTD**

SCHEDULE A

Country	Application No.	Filing Date	Patent No.	Grant Date
US	14/170,731	2/3/2014	9,018,062	4/28/2015
US	14/184,277	2/19/2014	9,245,977	1/26/2016
US	14/469,748	8/27/2014	9,171,921	10/27/2015
US	14/841,776	9/1/2015	9,905,636	2/27/2018
US	15/871,296	1/15/2018	10,290,715	5/14/2019
US	16/247,007	1/14/2019		
US	16/853,920	4/21/2020		
US	17/091,225	11/6/2020		
US	17/113,305	12/7/2020		
US	17/235,103	4/20/2021		
US	17/394,879	8/27/2021		
US	17/479,314	9/14/2021		
US	17/508,251	10/22/2021		